- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

These devices contain two independent $J-\overline{K}$ positive-edge-triggered flip-flops. A low level at the preset or clear inputs sets or resets the outputs regardless of the levels of the other inputs. When preset and clear are inactive (high), data at the J and \overline{K} inputs meeting the setup time requirements are transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the J and \overline{K} inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by grounding \overline{K} and tying J high. They also can perform as D-type flip-flops if J and \overline{K} are tied together.

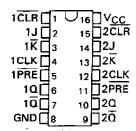
The SN54109 and SN54LS109A are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74109 and SN74LS109A are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each flip-flop)

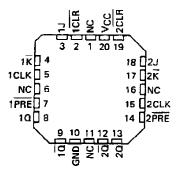
	IN	PUTS			OUT	PUTS
PRE	CLR	CLK	J	K	a	ā
L	Н	X	х	Х	H	L
н	L	×	X	X	L	Н
L	L	X	Х	Х	Нţ	Нţ
Н	н	f	L	L	L	Н
Н	H	t	Н	L	TOGG	GLE
н	Н	Ť	Ł	н	വു	$\overline{\alpha}_0$
н	Н	t	Н	н	Н	L
н	н	L	Х	х	Q ₀	ō₀ ·

 $^{^\}dagger$ The output levels in this configuration are not guaranteed to meet the minimum levels for V_{OH} if the lows at preset and clear are near V_{1L} maximum. Furthermore, this configuration is nonstable; that is, it will not persist when preset or clear return to their inactive (high) level.

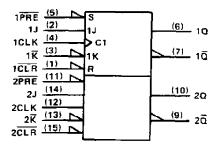
SN54109, SN54LS109A...J OR W PACKAGE SN74109...N PACKAGE SN74LS109A...D OR N PACKAGE (TOP VIEW)



SN54LS109A ... FK PACKAGE (TOP VIEW)



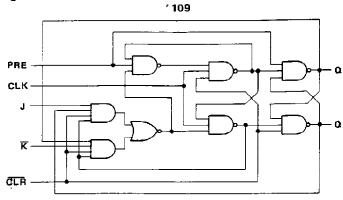
logic symbol‡



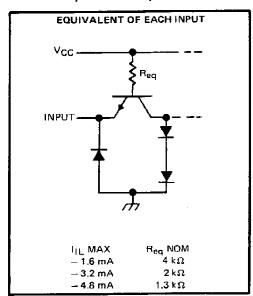
[‡]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

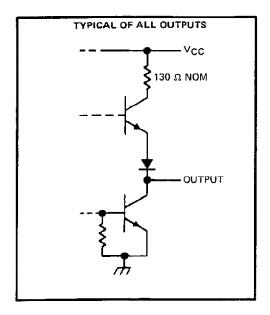
logic diagram (positive logic)

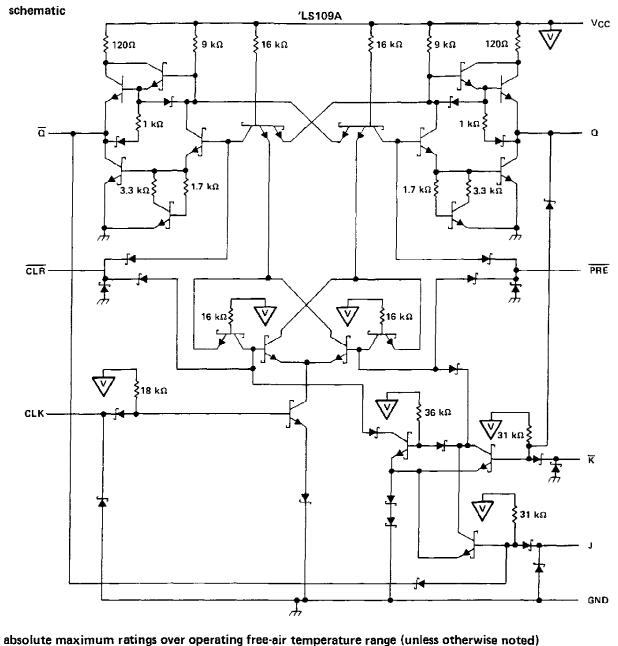


schematics of inputs and outputs



109





Supply voltage, VCC (see Note 1)	***************************************	7 V
Input voltage: '109	<u> </u>	5.5 V
'LS109A		
Operating free-air temperature range:	SN54'	- 55°C to 125°C
·	SN74'	0°C to 70°C
Storage temperature range	***************************************	- 65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



SN54109, SN74109 DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

recommended operating conditions

		-		SN5410	09	1	SN7410)9	UNIT
			MIN	MOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
٧ıL	Low-level input voltage			.,	8.0			0.8	V
ІОН	High-level output current				- 0.8			- 0.8	mA
IOL	Low-level output current				16			16	mA
	Pulse duration	CLK high or low	20			20			
tw.	Fuise duration	PRE or CLR low	20			20		T	ns
tsu	Input setup time before CLK 1	·	10			10			ns
t _{h_}	Input hold time-data after CLK1		6			6			ns
TΑ	Operating free-air temperature		~ 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAR.	AMETER		TEST CONDITI	onet		SN5410	9		SN7410	9	
1211	AIVIETEIS !		TEBT CONDITI		MIN	TYP‡	MAX	MIN	TYP#	MAX	דומט
VIK		V _{CC} = MIN,	= - 12 mA				- 1.5			- 1.5	V
Vон		V _{CC} = MIN, I _{OH} = - 0.8 mA	V _{IH} = 2 V,	V _{IL} ≈ 0.8 V,	2.4	3,4		2.4	3.4		v
VOL		V _{CC} = MIN, I _{OL} = 16 mA	V _{IH} = 2 V,	V _{IL} = 0.8 V,		0.2	0.4		0.2	0.4	٧
11		V _{CC} = MAX,	V _I = 5.5 V				1		·	1	mA
	J or K						40			40	
1	CLR	V _{CC} = MAX,	V. ~ 2.4.V				160			160	_
НІ	PRE or CLK	4GC - MIAA,	v ₁ - 2.4 v				80			80	μА
	Jor \overline{K}						- 1.6			- 1.6	
1	CLR1	V _{CC} = MAX,	V. = 0.4 W				- 4.8			- 4.8	mΑ
'IL	PRE¶	OCC - MAX,	V = 0.4 V				- 3.2			- 3.2	
	CLK		-	<u></u>			- 3.2			-3.2	
los §		V _{CC} = MAX			- 30		- 85	- 30	* ***	- 85	mA
ICC#		V _{CC} = MAX,	See Note 2		T	9	15		9	15	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: With all outputs open. ICC is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded,

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
fmax				25	33		MHz
tPLH	PRE	Q			10	15	ns
₹₽HL		ā			23	35	ns
^t PLH	CLR	ত্র	$R_L = 400 \Omega$, $C_L = 15 \rho F$		10	15	ns
tpHL	0211	a			17	25	ns
TPLH	CLK	QorQ			10	16	ns
tpHL_	OEK .	4314			18	28	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 \,^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time.

¹ Clear is tested with preset high and preset is tested with clear high.

[#] Average per flip-flop.

SN54LS109A, SN74LS109A DUAL J-K POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

recommended operating conditions

			s	N54LS1	09A	SI	N74LS1	A90	118117
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
v _{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.25	٧
v_{lH}	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			0.8	V
ТОН	High-level output current				- 0.4		••	- 0.4	mA
IOL	Low-level output current				4			8	mA
fclock	Clock frequency		0		25	0		25	MHz
	Dulan dunain	CLK high	25			25	_		
t _w	Pulse duration	PRE or CLR low	25			25			ns
	Beautiful before CLV 4	High-level data	35			35			
t _{su}	Setup time before CLK †	Low-level data	25			25			ns
th	Hold time-data after CLK †		5			5			ns
TA	Operating free-air temperature		- 55	*	125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITION	uet	SN	154LS10)9A	SN	174LS10	9A	
FARAINE I ER	1	TEST CONDITIO	49.	MIN	TYP#	MAX	MIN	TYP#	MAX	דומט
Vik	VCC - MIN,	I _I = - 18 mA	-			– 1.5		_	_ 1.5	V
VOH	V _{CC} = MIN, I _{OH} = - 0.4 mA	V _{IH} = 2 V,	V _{IL} = MAX,	2.5	3.4		2.7	3.4		V
	V _{CC} = MIN, I _{OL} = 4 mA	VIL = MAX,	V _{IH} = 2 V,		0.25	0,4		0.25	0.4	V
VOL	V _{CC} = MIN, I _{OL} = 8 mA	VIL = MAX,	V _{1H} = 2 V,					0.35	0.5	\ \ \
J, K or CLK	Vcc = MAX,	V ₁ = 7 V				0.1			0.1	_^
CLR or PRE	ACC - MINY	- V - Y V				0.2			0.2	mA
J, R or CLK	V _{CC} = MAX,	V ₁ = 2.7 V				20			20	
TH CLR or PRE	7 400 - 14122	V - 2.7 V				40			40	μΑ
J, K or CLK	VCC = MAX,	V _I = 0.4 V				- 0.4			- 0.4	
CLR or PRE	YCC - WAX,	V - 0.4 V				- 0.8			- 0.8	mA
OS§	VCC = MAX,	See Note 4	_	- 20	_	100	- 20		- 100	mA
ICC (Total)	V _{CC} = MAX,	See Note 2			4	8		4	8	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions,

NOTE 2: With all outputs open, ICC is measured with the Q and Q outputs high in turn. At the time of measurement, the clock input is grounded.

NOTE 4: For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with V_O = 2.25 V and 2.125 V for the 54 family and the 74 family, respectively with the minimum and maximum limits reduced to one half of their stated values.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	мах	UNIT
f _{max}				25	33		MHz
^t PLH	CLR, PRE	Q or Q	$R_L = 2 k\Omega$, $C_L = 15 pF$		13	25	ns
^t PHL_	or CLK				25	40	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C. §Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
JM38510/30109B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30109BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
JM38510/30109BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
JM38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/30109BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/30109SEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
JM38510/30109SEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
JM38510/30109SFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/30109SFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN74109N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74109N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS109AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS109AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS109AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS109AN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS109ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS109ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

PACKAGE OPTION ADDENDUM

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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
SN74LS109ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS109ANSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS109AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS109AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS109AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS109AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS109AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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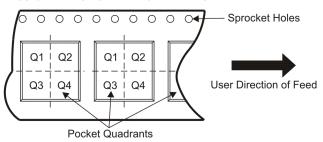
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

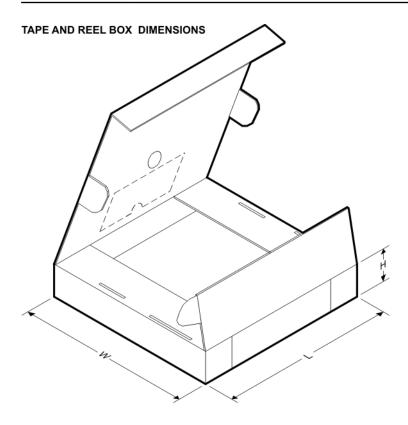
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS109ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS109ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS109ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS109ANSR	SO	NS	16	2000	346.0	346.0	33.0

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